LINEAR TECHNOLOGY MATERIALS DECLARATION

LT1763IS8-1.8#TRPBF		(Engineering Calculation)		SOIC		
(printed on: 7/26/2011 6:03:02 AM)					TOTAL MASS (g):	0.07439385
COMPONENT	VENDOR/	CONSTITUENT	CAS	CONSTITUENT	CONSTITUENT	CONSTITUENT
MATERIAL	INDUSTRY NAMES	NAME	NUMBER	MASS (g)	(PPM) OF MATERIAL	(PPM) OF TOTAL PKG.
Active Device	Linear Technology	Silicon (Si)	7440-21-3	0.002795	1000000	37570.31
Die Coat	Dow Corning	Silicone	67762-90-7	0	0	0
Lead Frame	Cu	Copper (Cu)	7440-50-8	0.023653	975000	317942.9
		Iron (Fe)	7439-89-6	0.000582	24000	7823.227
		Phosporus (P)	7723-14-0	7.00E-06	300	94.0938
		Zinc (Zn)	7440-66-6	1.70E-05	700	228.5135
		Nickel (Ni)	7440-02-0	0	0	0
		Silicon (Si)	7440-21-3	0	0	0
		Magnesium (Mg)	7439-95-4	0	0	0
		Tin (Sn)	7440-31-5	0	0	0
		Lead Frame Total:		0.024259	1000000	326088.8
Plating	PMI	Exter. Plating Pb	7439-92-1	0	0	0
		Exter. Plating Sn	7440-31-5	0.001476852	1000000	19851.8
		External Plating Total:		0.001476852	1000000	19851.8
		Inter. Plating Ni	7440-02-0	0	0	0
		Inter. Plating Ag	7440-22-4	6.80E-05	1000000	914.0541
		Internal Plating Total:		6.80E-05	1000000	914.0541
Die Attach	ELECTRICALLY CONDUCTIVE ADHESIVE	Silver (Ag)	7440-22-4	0.000876	750000	11775.17
		Tin (Sn)	7440-31-5	0	0	0
		Lead (Pb)	7439-92-1	0	0	0
		Silica (SiO2)	60676-86-0	0	0	0
		Metal Oxide		0	0	0
		Antimony (Sb)	7440-36-0	0	0	0
		Resin (EP)		0.000292	250000	3925.056
		Die Attach Total:		0.001168	1000000	15700.22
Encapsulation	MULTI-AROMATIC RESIN Br/Sb FREE	Resin (EP)		0.006657	150000	89483.2
		Bromine (Br)	40039-93-8	0	0	0
		Silica (SiO2)	60676-86-0	0.036392	820000	489180.2
		Antimony Trioxide (Sb2O3)	1309-64-4	0	0	0
		Metal Hydroxid		0.00111	25000	14920.59
		Carbon Black (C)	1333-86-4	0.000222	5000	2984.117
		Encapsulation Total:		0.044381	1000000	596568.1
Bond Wire Estimated	AFW/TANAKA/ Kn	Gold (Au)	7440-57-5	0.000246	1000000	3306.725
			TOTAL MASS (g):			0.07439385